

WS482 WATER SOLUBLE CORED WIRE

FEATURES

- Halide-Free, ORM0
- High Activity Level
- Excellent Thermal Transfer and Wetting
- Compatible with all Leaded and Lead-Free Alloys
- Extended Cleaning Window
- Residues Easily Removed with DI Water

DESCRIPTION

WS482 is a unique water soluble, halide-free flux cored wire solder. WS482 provides excellent wetting and soldering characteristics with a thermally robust formula allowing it to be processed with all leaded and lead-free solder alloys. WS482 post-process residues are non-corrosive and will not tarnish PCBs or bare copper. WS482 flux residue must be completely removed with DI water within 5-7 days of processing. WS482 flux classification is ORM0 per J-STD-004B.

STANDARD AVAILABILITY

WS482 cored wire is available in common alloys, diameters and spool sizes. Non-common alloys, diameters and spool sizes may be available upon special request. Contact AIM for detailed availability information.

APPLICATION

Solder iron tip temperature should be between 350° - 400°C (650° - 750°F) for lead bearing alloys, 370° - 425°C (700° - 800°F) for common lead-free alloys.



HANDLING & STORAGE

Time	Parameters
3 years	Cool < 30°C (< 86°F) Dry < 75%Rh

Store cored wire in a clean, dry area away from moisture and sunlight. Do not freeze this product.

CLEANING

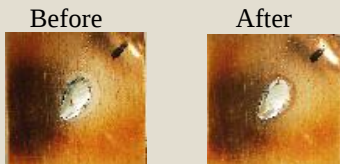
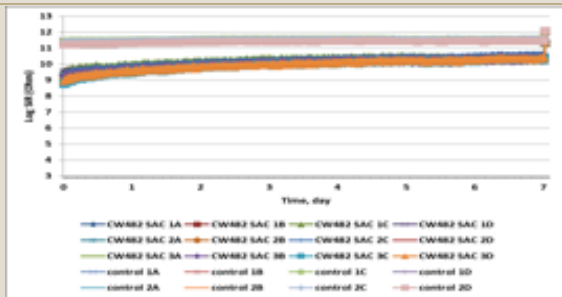
Post-process residues should be removed with deionized water at 38° - 60°C (100° - 140°F). An in-line or other pressurized spray cleaning system is recommended.

SAFETY

Use with adequate ventilation and proper personal protective equipment. Refer to the accompanying Safety Data Sheet for any specific emergency information. Do not dispose of any hazardous materials in non-approved containers.

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TEST DATA SUMMARY

Name	Test Method	Results	
IPC Flux Classification	J-STD-004	ORM0	
IPC Flux Classification	J-STD-004B 3.3.1	ORM0	
Name	Test Method	Typical Results	Image
Copper Mirror	J-STD-004B 3.4.1.1 IPC-TM-650 2.3.32	LOW	
Corrosion	J-STD-004B 3.4.1.2 IPC-TM-650 2.6.15	PASS	
Quantitative Halides	J-STD-004B 3.4.1.3 IPC-TM-650 2.3.28.1	0.0%	
Qualitative Halides, Silver Chromate	J-STD-004B 3.5.1.1 IPC-TM-650 2.3.33	PASS *Discoloration due to amine reaction	
Qualitative Halides, Fluoride Spot	J-STD-004B 3.5.1.2 IPC-TM-650 2.3.35.1	No Fluoride	
Surface Insulation Resistance *After Cleaning	J-STD-004B 3.4.1.4 IPC-TM-650 2.6.3.7	All measurements on test patterns exceed 100 MΩ	
Acid Value Determination	J-STD-004B 3.4.2.2 IPC-TM-650 2.3.13	119 mgKOH/g flux Typical	
Visual	J-STD-004B 3.4.2.5	PASS	
Wetting	J-STD-005A 3.9 IPC-TM-650 2.4.45	PASS	
Spread	J-STD-004B 3.7.2 IPC-TM650 2.4.46	PASS	
Cleanliness	TM125-03	PASS	

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